Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.110”**

**.110”**

**B**

**E**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: B = .020” X .033” E = .018” X .030”**

**Backside Potential: COLLECTOR**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .110” X .110” DATE: 9/8/21**

**MFG: MOTOROLA THICKNESS .010” P/N: 2N6650**

**DG 10.1.2**

#### Rev B, 7/1